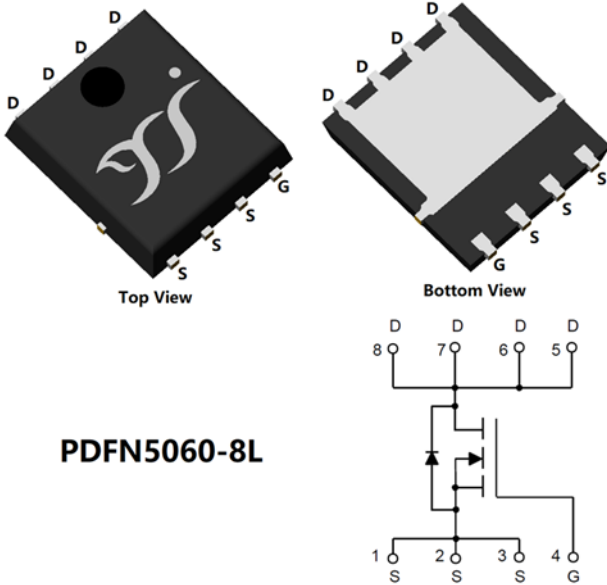


N-Channel Enhancement Mode Field Effect Transistor



PDFN5060-8L

Product Summary

- V_{DS} 60V
- I_D 30A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <20mohm
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) <23mohm
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Trench Power MV MOSFET technology
- High density cell design for Low $R_{DS(ON)}$
- High Speed switching
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- DC-DC Converters
- Power management functions
- Backlighting

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	60	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current	I_D	$T_C=25^\circ C$	30
		$T_C=100^\circ C$	19
Pulsed Drain Current ^A	I_{DM}	130	A
Total Power Dissipation @ $T_C=25^\circ C$	P_D	45	W
Single Pulse Avalanche Energy ^B	E_{AS}	100	mJ
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	2.8	$^\circ C/W$
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	$^\circ C$

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG30N06A	F1	YJG30N06A	5000	10000	100000	13" reel



YJG30N06A

■ Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=15A$		16	20	m Ω
		$V_{GS}=4.5V, I_D=10A$		17.5	23	
Diode Forward Voltage	V_{SD}	$I_S=10A, V_{GS}=0V$		0.85	1.2	V
Maximum Body-Diode Continuous Current	I_S				30	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=30V, V_{GS}=0V, f=1\text{MHz}$		2027		pF
Output Capacitance	C_{oss}			132		
Reverse Transfer Capacitance	C_{rss}			116		
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=30V, I_D=10A$		51		nC
Gate-Source Charge	Q_{gs}			8.1		
Gate-Drain Charge	Q_{gd}			11.4		
Reverse Recovery Charge	Q_{rr}	$I_F=20A, di/dt=500A/\mu s$		11.4		ns
Reverse Recovery Time	t_{rr}			22		
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=30V, I_D=2A, R_{GEN}=3\Omega$		11		ns
Turn-on Rise Time	t_r			21		
Turn-off Delay Time	$t_{D(off)}$			40		
Turn-off fall Time	t_f			23		

A. Pulse Test: Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

B. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design, while $R_{\theta JA}$ is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



■ Typical Performance Characteristics

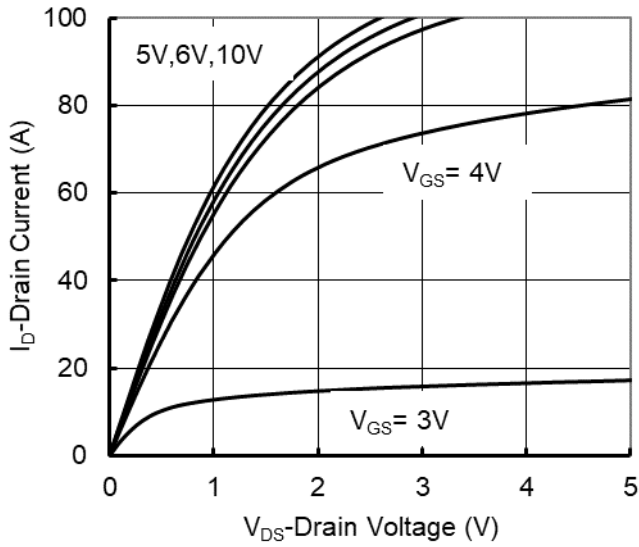


Figure 1. Output Characteristics

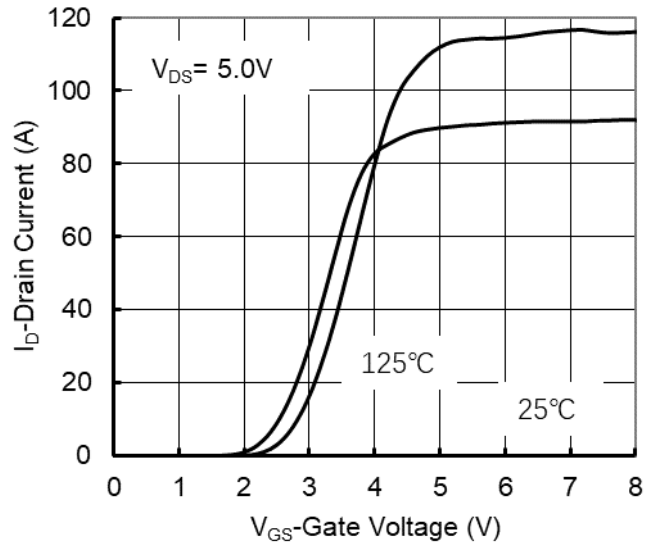


Figure 2. Transfer Characteristics

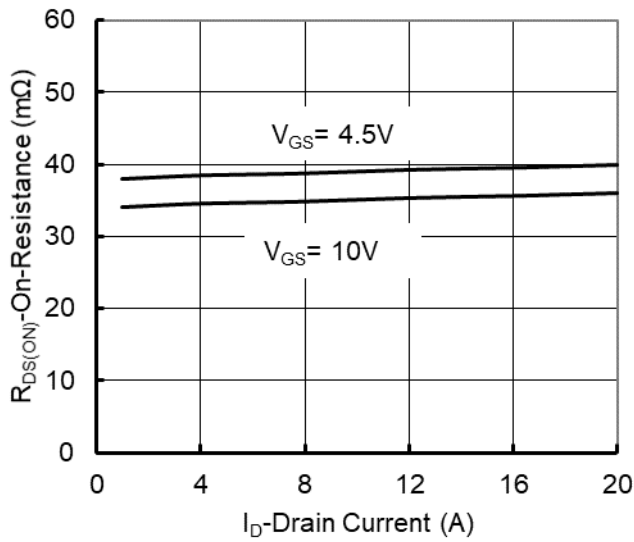


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

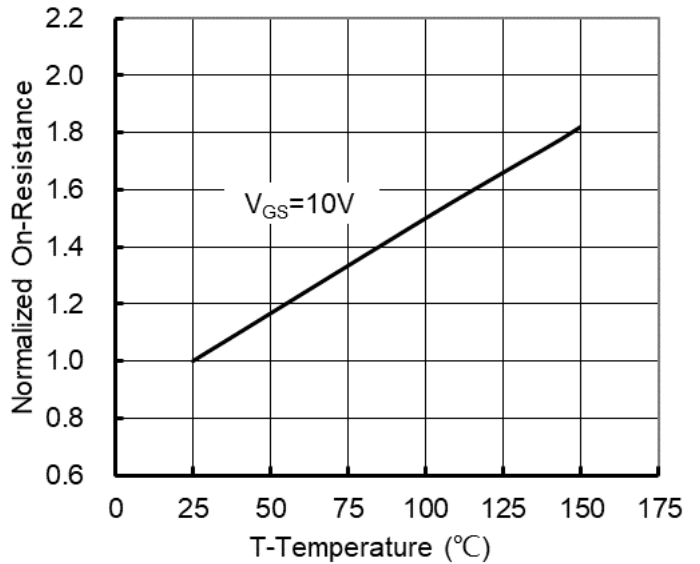


Figure 4. On-Resistance vs. Junction Temperature

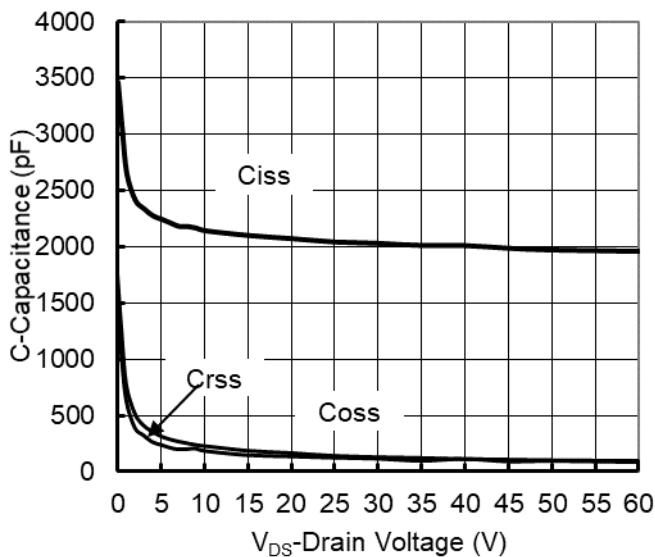


Figure 5. Capacitance Characteristics

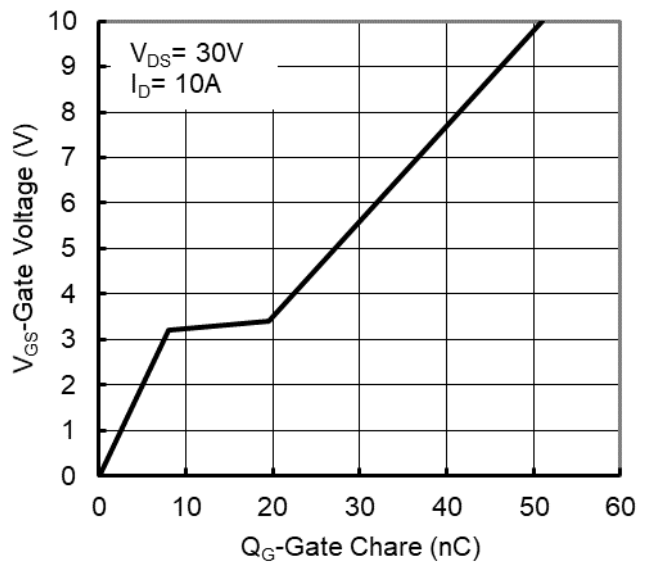


Figure 6. Gate Charge



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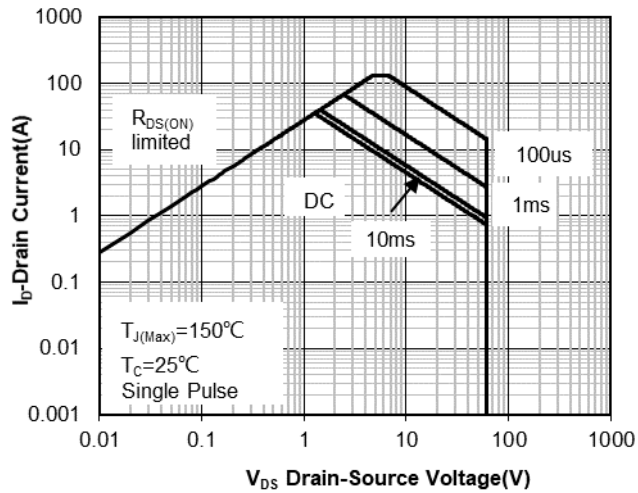


Figure 7. Safe Operation Area

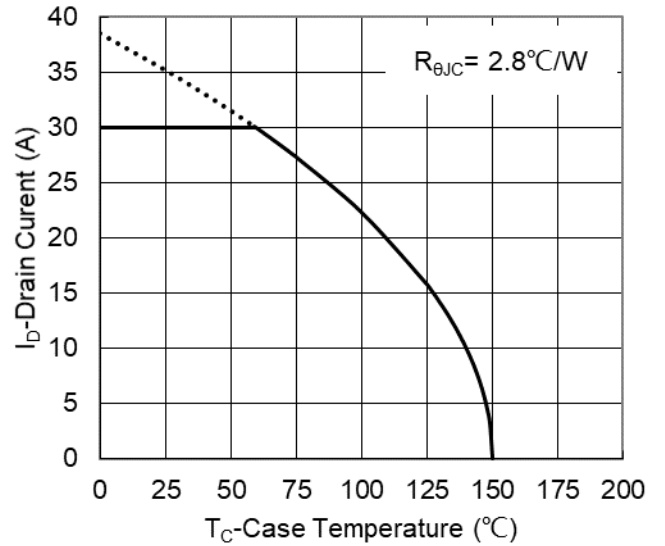


Figure 8. Maximum Continuous Drain Current vs Case Temperature

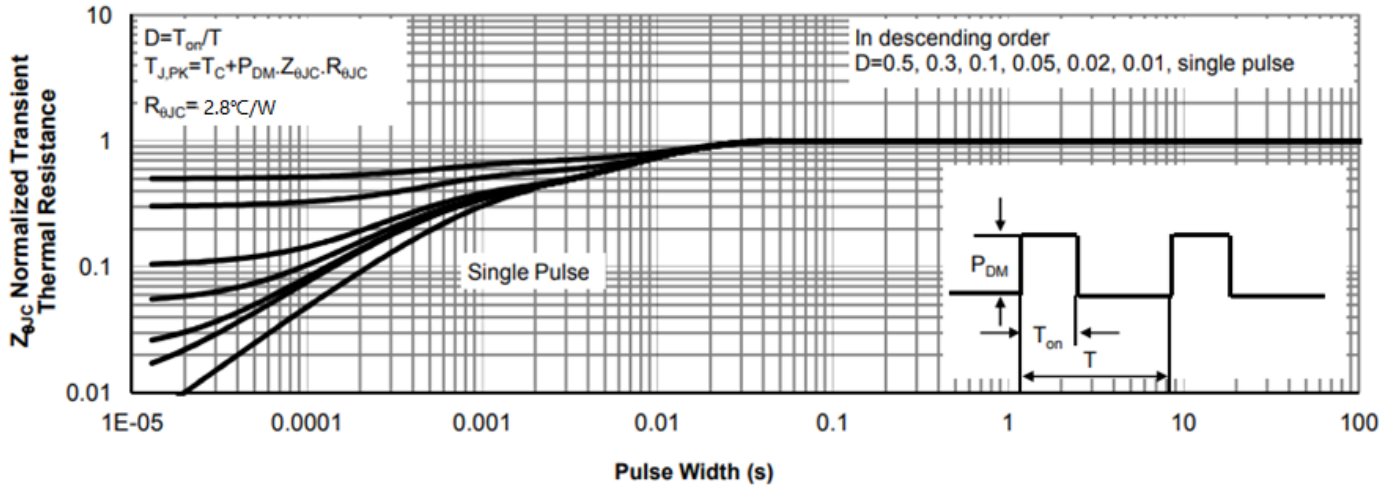
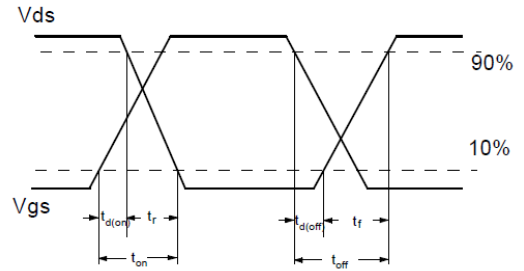
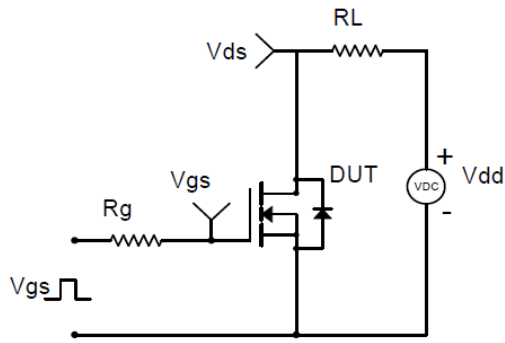
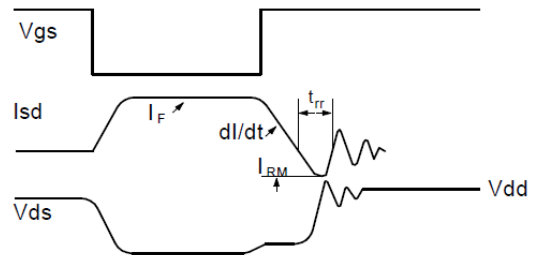
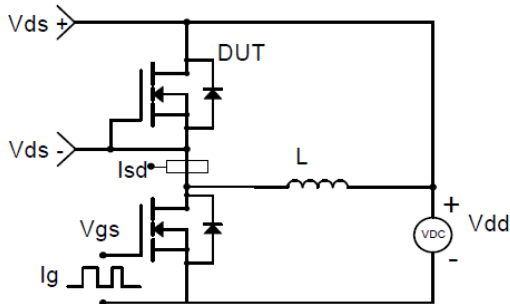


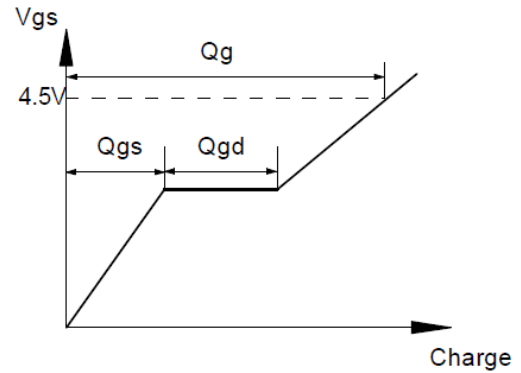
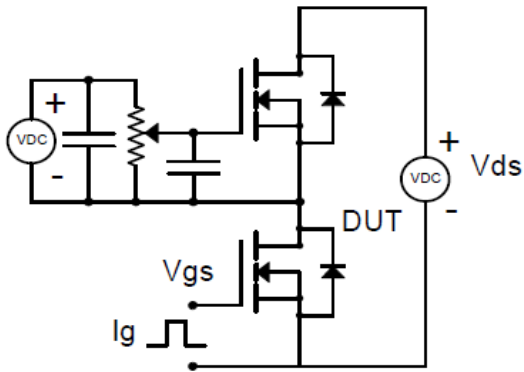
Figure 9. Normalized Maximum Transient Thermal Impedance



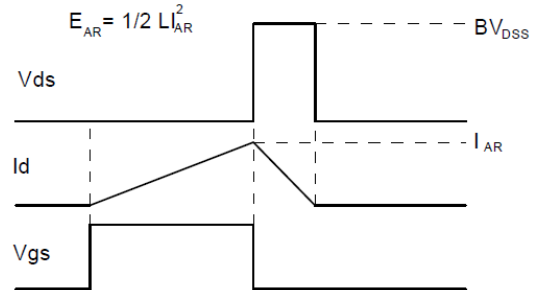
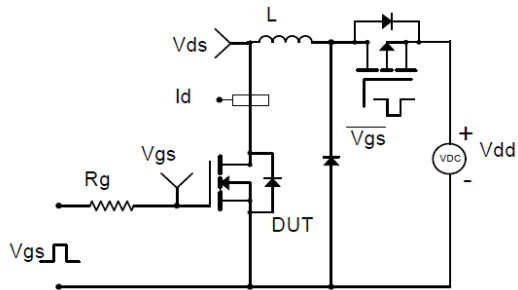
Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Gate Charge Test Circuit & Waveform

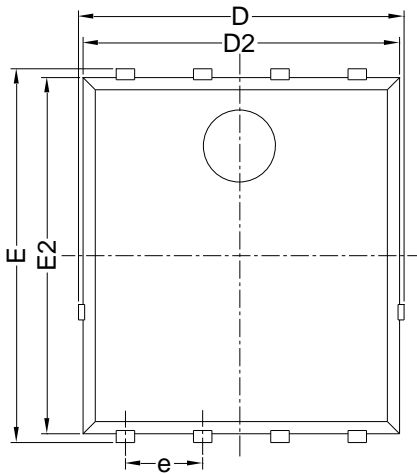


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

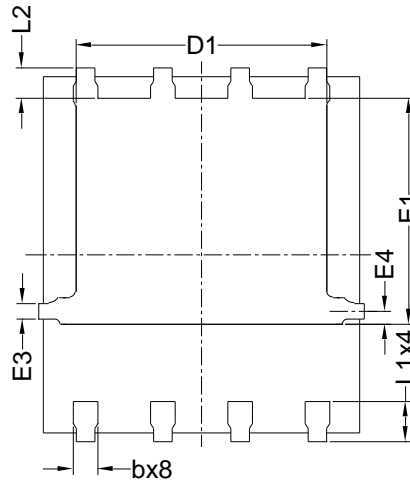


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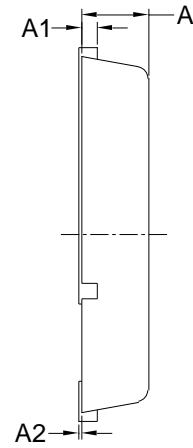
■ PDFN5060-8L-B-1.1MM Package Information



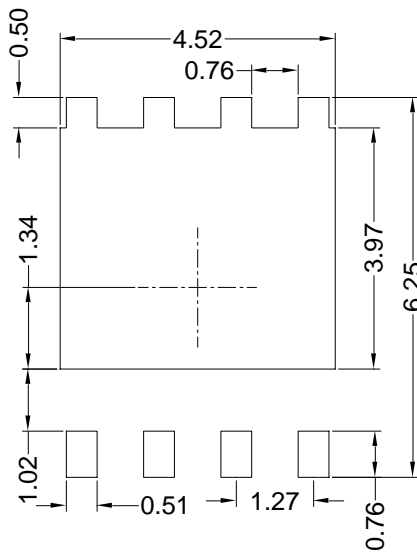
Top View
正面视图



Bottom View
背面视图



Side View
侧面视图



Suggested Solder Pad Layout
Top View

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.15	6.35
A	1.00	1.10	1.20
A1	0.254 BSC		
A2			0.10
D1	3.92	4.12	4.32
E1	3.52	3.72	3.92
D2	5.00	5.20	5.40
E2	5.66	5.86	6.06
E3	0.254 REF		
E4	0.21 REF		
L1	0.56	0.66	0.76
L2	0.50 BSC		
b	0.31	0.41	0.51
e	1.27 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.10 mm.
3. The pad layout is for reference purposes only.



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